

# McDermott Will & Emery

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Confirmation No.: 1077  
Examiner: M. Dahimene  
Art Unit: 1765

U.S. Patent & Trademark Office

571.273.8300

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From:	John A. Hankins
E-Mail:	jhankins@mwe.com
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Client/Matter/Tkpr:	050432-0616

Direct Phone: 858.643.1423

Direct Fax: 858.597.1585

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Re: U.S. Patent Application No. 10/728,772

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Message:

Official Transmission

Attached please find:

Transmittal (1 page)

Amendment (9 pages)

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U.S. practice conducted through McDermott Will & Emery LLP.

4370 La Jolla Village Drive Suite 700 San Diego, California 92122-1252 Telephone: 858.535.9001

Docket No.: 050432-0616

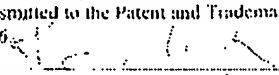
**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Seung-Hyun RHEE  
 Appl. No. : 10/728,772  
 Filed : December 8, 2003  
 Title : A METHOD OF FORMING AN  
 INTERLEVEL DIELECTRIC LAYER  
 EMPLOYING DIELECTRIC ETCH-BACK  
 PROCESS WITHOUT EXTRA MASK SET

Customer No.: 41552  
 Confirmation No.: 1077

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile  
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 2006.

  
 Brenda Lewis

Grp./A.U. : 1765  
 Examiner: : Mahmoud Dahimene

Mail Stop AP  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is Request for Reconsideration in the above-identified application.

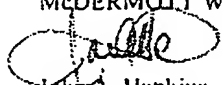
- ☒ No additional fee is required.  
☐ Applicant is entitled to small entity status under 37 CFR 1.27  
☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	17	17	0	\$50.00	\$0.00
Independent Claims	2	2	0	\$200.00	\$0.00
Multiple dependent claims newly presented					\$0.00
Basic Filing Fee					\$0.00
Surcharge Fee					\$0.00
Search Fee					\$0.00
Examination Fee					\$0.00
Fee for extension of time					\$0.00
Total of Above Calculations					\$0.00

- ☐ Please charge my Deposit Account No. 502624 in the amount of \$ \_\_\_\_\_. An additional copy of this transmittal sheet is submitted herewith.  
☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment to Deposit Account No. 502624, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,  
 McDERMOTT WILL & EMERY LLP

  
 John A. Hankins

Registration No. 32,029

Please recognize our Customer No. 41552 as our  
 correspondence address.

4370 La Jolla Village Drive, Suite 700  
 San Diego, CA 92122  
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 Date: April 4, 2006

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PATENT**

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Brenda Lewis

Grp./A.U. : 1765  
Examiner : Mahmoud Dahmane

**REQUEST FOR RECONSIDERATION UNDER CFR 1.116**

Mail Stop A1  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This Request for Reconsideration is respectfully submitted in response to the Final Office

Action dated January 4, 2006.

A listing of the Claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.